

Title (en)
Piezoelectric device

Title (de)
Piezoelektrische Vorrichtung

Title (fr)
Dispositif piézoélectrique

Publication
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Application
EP 02010404 A 20020508

Priority
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Abstract (en)
[origin: EP1257055A2] A package (1) has a first region (7a) and a second region (7b) on a top side and has a base comprising a ceramic board (7) where wiring patterns (14) for connecting a quartz crystal resonator (2) and an IC chip (3) for driving it are formed. In the base, a first sidewall (9) enclosing the first region is arranged on the top side of the board and the quartz crystal resonator is mounted in a first space (8) delimited by the first sidewall, and the IC chip is mounted in a second space (10) delimited by a second sidewall (11) enclosing the second region (7b). The first sidewall is formed higher than the second sidewall, a metal cover (13) is seam welded at the upper end thereof, and the first void space is sealed in a vacuum or nitrogen atmosphere. The IC chip of the second region is resin sealed. <IMAGE>

IPC 8 full level
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